Do Not Mount: U1, L1, C2 and C3; add a wire from J1-2 to J12-2 (connect VCC_IN to VCC_430) to bypass TPS62730
You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Note

ZZ2
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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